

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

| | |
|----------------------|------------------------------------------------------------------------------------------------------------------------|
| 1.1 Company |  STMicroelectronics International N.V |
| 1.2 PCI No. | POWER AND DISCRETES/25/16034 |
| 1.3 Title of PCI | Sealing process change for Diodes and Power MOSFETs in SMD.5 and TO257AA packages. |
| 1.4 Product Category | All ESCC Diodes and Power MOSFETs assembled in SMD.5 and TO-257AA packages. |
| 1.5 Issue date | 2025-12-28 |

2. PCI Team

| | |
|---------------------------|-----------------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Stephane CHAMARD,Rosario RUGGERI |
| 2.1.2 Marketing Manager | Philippe LEGER, Giuseppe CAMONITA |
| 2.1.3 Quality Manager | Emmanuelle GUERINEL |

3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|--------------|-------------------------------------------------------|-------------------------------------|
| Methods | Change in process technique for molding/encapsulation | ST Microelectronics Rennes - France |

4. Description of change

| | Old | New |
|---------------------------------------------------------------------------------------|-----------------------|-----------------|
| 4.1 Description | Parallel seam welding | Furnace sealing |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No | |

5. Reason / motivation for change

| | |
|----------------------|---------------------------------------------------------------------------|
| 5.1 Motivation | This change increases production capacity and ensures service continuity. |
| 5.2 Customer Benefit | SERVICE CONTINUITY |

6. Marking of parts / traceability of change

| | |
|-----------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 6.1 Description | New Finished Good print on labels. Date code, written on the parts and on the Certificate of Conformance, fully identifies the parts' manufacturing flow. |
|-----------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2025-12-31 |
| 7.2 Intended start of delivery | 2026-02-01 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | |
|----------------------------------------------------|-------------|
| 8.1 Description | |
| 8.2 Qualification report and qualification results | In progress |

9. Attachments (additional documentations)

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|-------------------------------------------------------------------------------------------|
| 16034 Public product.pdf 16034 Oven sealing on diodes and pwmos SMD_5 TO257AA rev1.pdf |
|-------------------------------------------------------------------------------------------|

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | STPS60A150CS1 | |

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